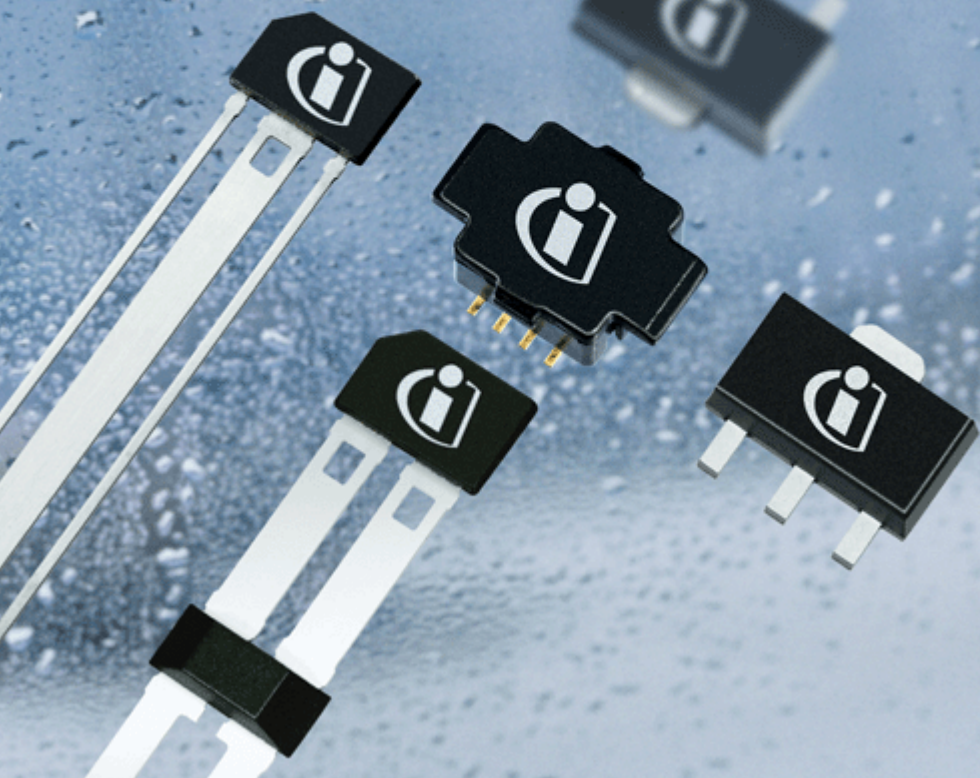


# TLI4966G

High Precision Hall-Effect Switch with  
Direction Detection



Sensors



Never stop thinking

**Edition 2018-12-11**

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Rev 1.0

Previous Version:

| Page | Subjects (major changes since last revision) |
|------|--|
|      |  |
|      |  |
|      |  |

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## 1 Overview

### 1.1 Features

- 2.7 V to 24 V supply voltage operation
- Operation from unregulated power supply
- High sensitivity and high stability of the magnetic switching points
- High resistance to mechanical stress by Active Error Compensation
- Reverse battery protection (-18 V)
- Superior temperature stability
- Peak temperatures up to 125°C without damage
- Low jitter (typ. 1  $\mu$ s)
- Digital output signals
- Bipolar version
- Excellent matching between the 2 Hall probes
- Hall plate distance 1.45 mm
- Direction & speed information
- Direction signal switches before the speed signal
- SMD package PG-TSOP6-6-9



### 1.2 Functional Description

The TLI4966G is an integrated circuit double Hall-effect sensor designed specifically for industrial applications. Precise magnetic switching points and high temperature stability are achieved by active compensation circuits and chopper techniques on chip. They provide a speed signal at Q2 for every magnetic pole pair and a direction information at Q1, which is provided before the speed signal.

| Type     | Ordering Code | Package      |
|----------|---------------|--------------|
| TLI4966G | SP003330332   | PG-TSOP6-6-9 |

### 1.3 Pin Configuration (top view)

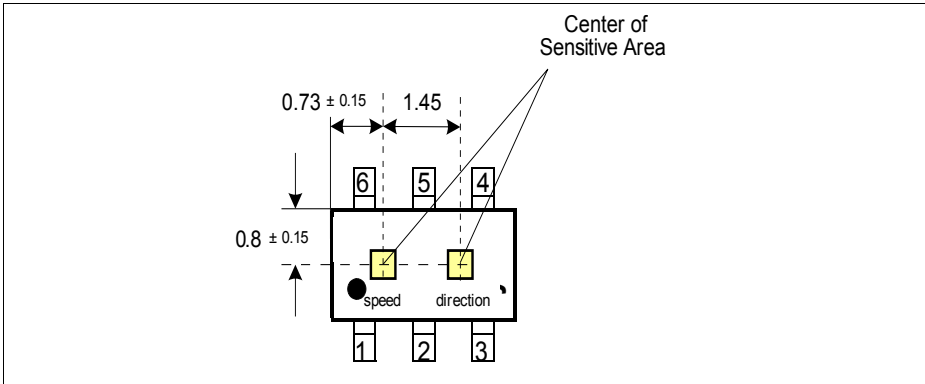


Figure 1 Pin Definition and Center of Sensitive Area

Table 1 Pin Definitions and Functions PG-TSOP6-6-9

| Pin No. | Symbol | Function                      |
|---------|--------|-------------------------------|
| 1       | Q2     | Speed                         |
| 2       | GND    | Recommended connection to GND |
| 3       | Q1     | Direction                     |
| 4       | $V_S$  | Supply voltage                |
| 5       | GND    | Recommended connection to GND |
| 6       | GND    | Ground                        |

## 2 General

### 2.1 Block Diagram

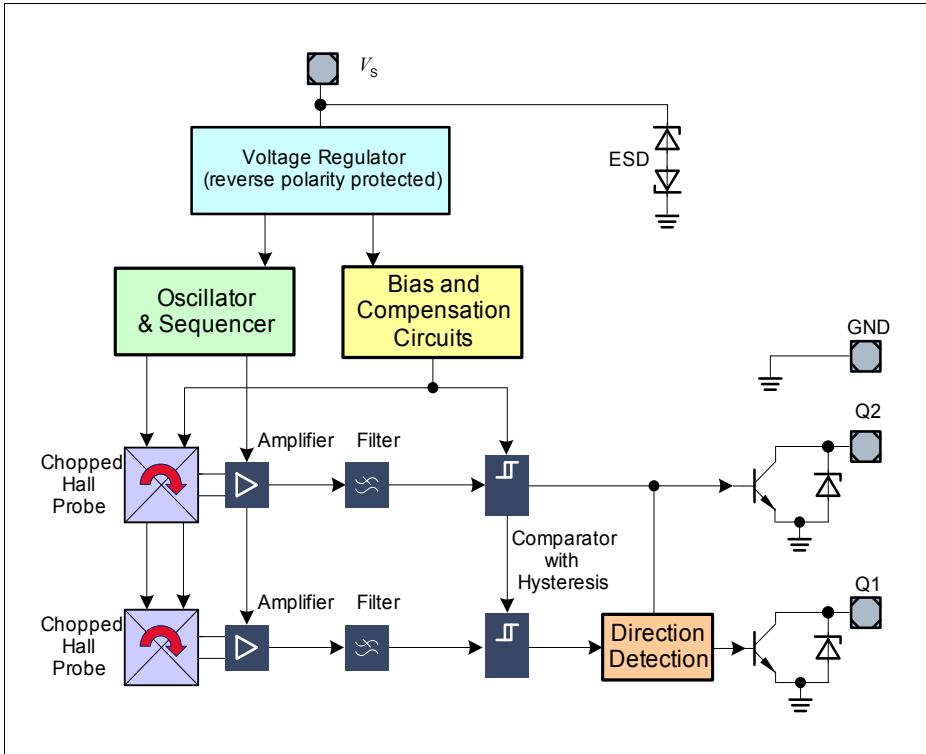


Figure 2 Block Diagram

### 2.2 Circuit Description

The chopped Double Hall Switch comprises two Hall probes, bias generator, compensation circuits, oscillator, and output transistors.

The bias generator provides currents for the Hall probes and the active circuits. Compensation circuits stabilize the temperature behavior and reduce technology variations.

The Active Error Compensation rejects offsets in signal stages and the influence of mechanical stress to the Hall probes caused by molding and soldering processes and other thermal stresses in the package. This chopper technique together with the threshold generator and the comparator ensures high accurate magnetic switching points.



### 3 Maximum Ratings

**Table 2 Absolute Maximum Ratings**

| Parameter                                | Symbol | Limit Values      |                | Unit | Conditions   |
|--|--------|-------------------|----------------|------|--|
|  |        | min.              | max.           |      |  |
| Supply voltage                           | $V_S$  | -18<br>-18<br>-18 | 18<br>24<br>26 | V    | for 1 h, $R_S \geq 200 \Omega$<br>for 5 min, $R_S \geq 200 \Omega$ |
| Supply current through protection device | $I_S$  | -50               | 50             | mA   |  |
| Output voltage                           | $V_Q$  | -0.7<br>-0.7      | 18<br>26       | V    | for 5 min @ 1.2 k $\Omega$ pull up                                 |
| Continuous output current                | $I_Q$  | -50               | 50             | mA   |  |
| Junction temperature                     | $T_J$  | -40               | 125            | °C   |  |
| Storage temperature                      | $T_S$  | -40               | 150            | °C   |  |
| Magnetic flux density                    | $B$    | –                 | unlimited      | mT   |  |

*Note: Stresses above those listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.*

**Table 3 ESD Protection <sup>1)</sup>**

| Parameter   | Symbol    | Limit Values |         | Unit | Notes  |
|-------------|-----------|--------------|---------|------|--|
|             |           | min.         | max.    |      |  |
| ESD voltage | $V_{ESD}$ | –            | $\pm 4$ | kV   | HBM, $R = 1.5 \text{ k}\Omega$ ,<br>$C = 100 \text{ pF}$<br>$T_A = 25^\circ\text{C}$ |

1) Human Body Model (HBM) tests according to: EOS/ESD Association Standard S5.1-1993 and Mil. Std. 883D method 3015.7

## 4 Operating Range

**Table 4 Operating Range**

| Parameter           | Symbol | Limit Values  |             |                | Unit | Conditions  |
|---------------------|--------|---------------|-------------|----------------|------|---|
|                     |        | min.          | typ.        | max.           |      |   |
| Supply voltage      | $V_S$  | 2.7<br>–<br>– | –<br>–<br>– | 18<br>24<br>26 | V    | 1 h with $R_S \geq 200 \Omega$<br>for 5 min $R_S \geq 200 \Omega$ |
| Output voltage      | $V_Q$  | -0.7          | –           | 18             | V    |   |
| Ambient temperature | $T_A$  | -40           |             | 115            | °C   |   |
| Output current      | $I_Q$  | 0             | –           | 10             | mA   |   |

## 5 Electrical and Magnetic Parameters

**Table 5 Electrical Characteristics** <sup>1)</sup>

| Parameter  | Symbol      | Limit Values |      |                  | Unit                | Conditions   |
|--|-------------|--------------|------|------------------|---------------------|--|
|  |             | min.         | typ. | max.             |                     |  |
| Supply current                                     | $I_S$       | 4            | 5.2  | 7                | mA                  | $V_S = 2.7 \text{ V} \dots 18 \text{ V}$   |
| Reverse current                                    | $I_{SR}$    | 0            | 0.2  | 1                | mA                  | $V_S = -18 \text{ V}$  |
| Output saturation voltage                          | $V_{QSAT}$  | –            | 0.3  | 0.6              | V                   | $I_Q = 10 \text{ mA}$  |
| Output leakage current                             | $I_{QLEAK}$ | –            | 0.05 | 10               | $\mu\text{A}$       | for $V_Q = 18 \text{ V}$   |
| Output fall time                                   | $t_f$       | –            | 0.2  | 1                | $\mu\text{s}$       | $R_L = 1.2 \text{ k}\Omega$ ; $C_L < 50 \text{ pF}$<br>see:<br><a href="#">Figure 3 on Page 13</a> |
| Output rise time                                   | $t_r$       | –            | 0.2  | 1                | $\mu\text{s}$       |  |
| Chopper frequency                                  | $f_{OSC}$   | –            | 320  | –                | kHz                 |  |
| Switching frequency                                | $f_{SW}$    | 0            | –    | 15 <sup>2)</sup> | kHz                 |  |
| Delay time <sup>3)</sup>                           | $t_d$       | –            | 13   | –                | $\mu\text{s}$       |  |
| Count Signal Delay                                 | $t_{dc}$    | 50           | 200  | 1000             | ns                  |  |
| Output jitter <sup>4)</sup>                        | $t_{QJ}$    | –            | 1    | –                | $\mu\text{s}_{RMS}$ | Typ. value for square-wave signal 1 kHz  |
| Repeatability of magnetic thresholds <sup>5)</sup> | $B_{REP}$   | –            | 40   | –                | $\mu\text{T}_{RMS}$ | Typ. value for $\Delta B/\Delta t > 12 \text{ mT/ms}$  |
| Power-on time <sup>6)</sup>                        | $t_{PON}$   | –            | 13   | –                | $\mu\text{s}$       | $V_S \geq 2.7 \text{ V}$   |
| Distance of hall plates                            | $d_{HALL}$  | –            | 1.45 | –                | mm                  |  |
| Thermal resistance <sup>7)</sup>                   | $R_{thJA}$  | –            | 100  | –                | K/W                 | PG-TSOP6-6-9   |

1) over operating range, unless otherwise specified. Typical values correspond to  $V_S = 12 \text{ V}$  and  $T_A = 25^\circ\text{C}$

2) To operate the sensor at the max. switching frequency, the magnetic signal amplitude must be 1.4 times higher than for static fields. This is due to the -3 dB corner frequency of the low pass filter in the signal path.

3) Systematic delay between magnetic threshold reached and output switching

4) Jitter is the unpredictable deviation of the output switching delay

5)  $B_{REP}$  is equivalent to the noise constant

6) Time from applying  $V_S \geq 2.7 \text{ V}$  to the sensor until the output state is valid

7) Thermal resistance from junction to ambient

**Electrical and Magnetic Parameters**
**Calculation of the junction temperature (PG-TSOP6-6-9 example)**

e.g. for  $V_S = 12.0\text{ V}$ ,  $I_{S\max} = 7.0\text{ mA}$ ,  $V_{QSAT\text{typ}} = 0.3\text{ V}$  and  $2 \times I_Q = 10\text{ mA}$  :

Power Dissipation:  $P_{\text{DIS}} = 90.0\text{ mW}$ .

In  $T_J = T_A + (R_{\text{thJA}} \times P_{\text{DIS}})$  / for  $T_A = 115^\circ\text{C} + (100\text{ K/W} \times 0.09\text{ W})$

Resulting max. junction temperature:  $T_J = 124.0^\circ\text{C}$

**Table 6 Magnetic Characteristics <sup>1)</sup>**

| Parameter                                       | Symbol             | $T_J$ [ $^\circ\text{C}$ ] | Limit Values |      |      | Unit                  | Conditions   |
|---|--------------------|----------------------------|--------------|------|------|-----------------------|--|
|   |                    |                            | min.         | typ. | max. |                       |  |
| Operate point                                   | $B_{\text{OP}}$    | -40                        | 5.2          | 7.7  | 10.3 | mT                    |  |
|   |                    | 25                         | 5.0          | 7.5  | 10.0 |                       |  |
|   |                    | 125                        | 4.7          | 7.1  | 9.5  |                       |  |
| Release point                                   | $B_{\text{RP}}$    | -40                        | -10.3        | -7.7 | -5.2 | mT                    |  |
|   |                    | 25                         | -10.0        | -7.5 | -5.0 |                       |  |
|   |                    | 125                        | -9.5         | -7.1 | -4.7 |                       |  |
| Hysteresis                                      | $B_{\text{HYS}}$   | -40                        | –            | –    | –    | mT                    |  |
|   |                    | 25                         | 10.0         | 15.0 | 20.0 |                       |  |
|   |                    | 125                        | –            | –    | –    |                       |  |
| Magnetic matching                               | $B_{\text{MATCH}}$ | -40                        | –            | –    | –    | mT                    | Valid for<br>$B_{\text{OP1}} - B_{\text{OP2}}$<br>and<br>$B_{\text{RP1}} - B_{\text{RP2}}$ |
|   |                    | 25                         | -2.0         | 0    | 2.0  |                       |  |
|   |                    | 125                        | –            | –    | –    |                       |  |
| Magnetic offset                                 | $B_{\text{OFF}}$   | -40                        | –            | –    | –    | mT                    | $(B_{\text{OP}} + B_{\text{RP}})/2$  |
|   |                    | 25                         | -2.0         | 0    | 2.0  |                       |  |
|   |                    | 125                        | –            | –    | –    |                       |  |
| Temperature compensation of magnetic thresholds | $TC$               | –                          | –            | -350 | –    | ppm/ $^\circ\text{C}$ |  |

1) over operating range, unless otherwise specified. Typical values correspond to  $V_S = 12\text{ V}$

*Note: Typical characteristics specify mean values expected over the production spread.*

**Field Direction Definition**

Positive magnetic fields related with south pole of magnet to the branded side of package.

## Timing Diagrams for the Speed and Direction Outputs

## 6 Timing Diagrams for the Speed and Direction Outputs

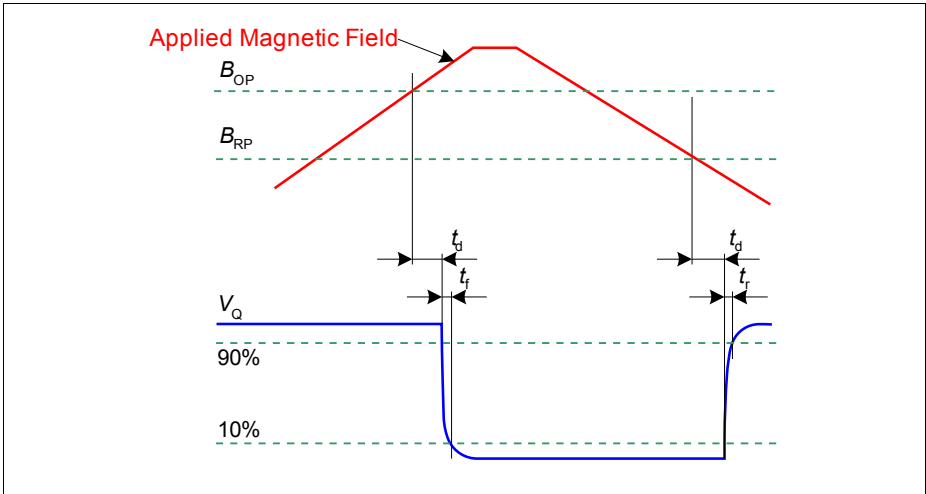


Figure 3 Timing Definition of the Speed Signal

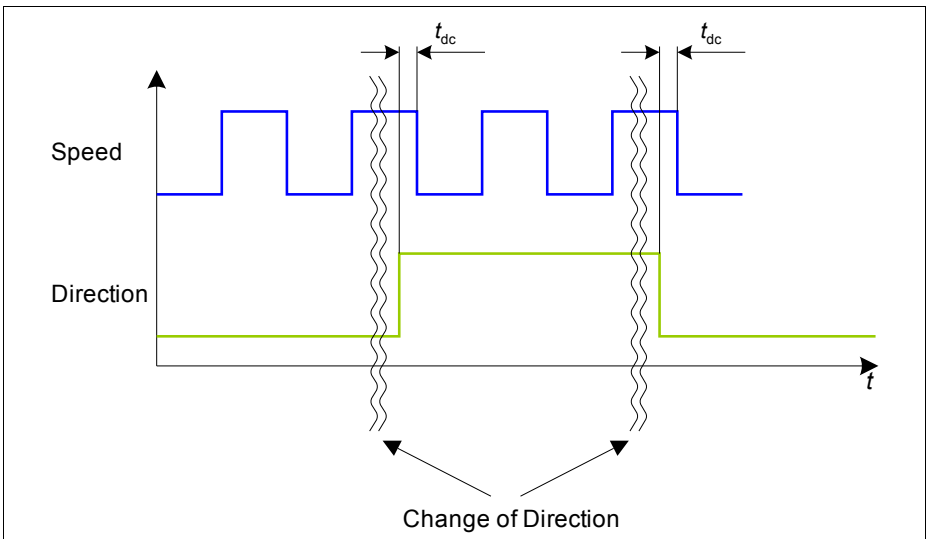
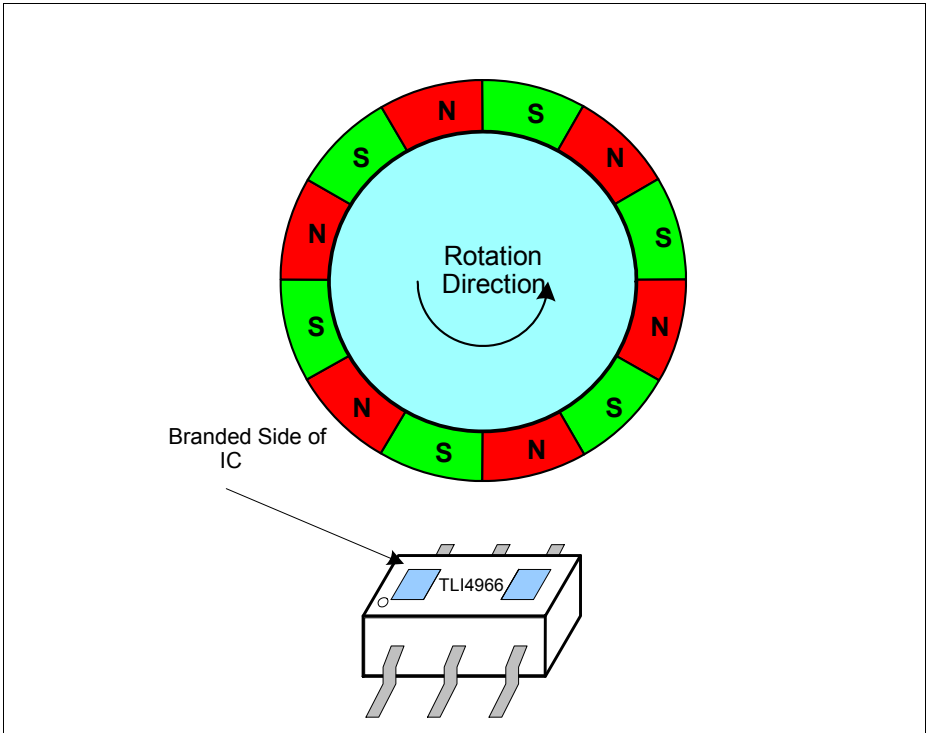


Figure 4 Timing Definition of the Direction Signal

Timing Diagrams for the Speed and Direction Outputs



**Figure 5 Definition of the Direction Signal**

| Rotation Direction | State of Direction Output $V_{Q1}$ |
|--------------------|------------------------------------|
| Left to right      | Low                                |
| Right to left      | High                               |

## 7 Package Information

### 7.1 Package Marking

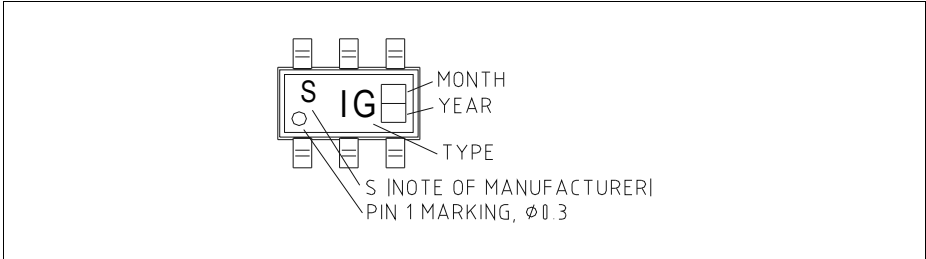


Figure 6 Marking PG-TSOP6-6-9

### 7.2 Distance between Chip and Package Surface

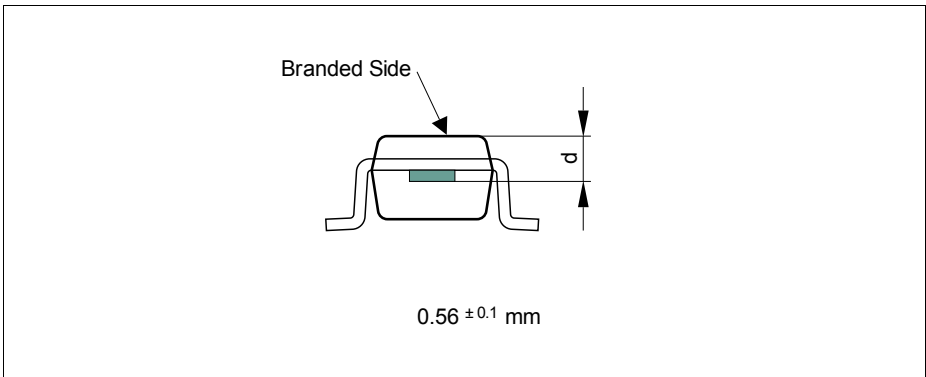


Figure 7 Distance Chip to Upper Side of IC

### 7.3 Package Outlines

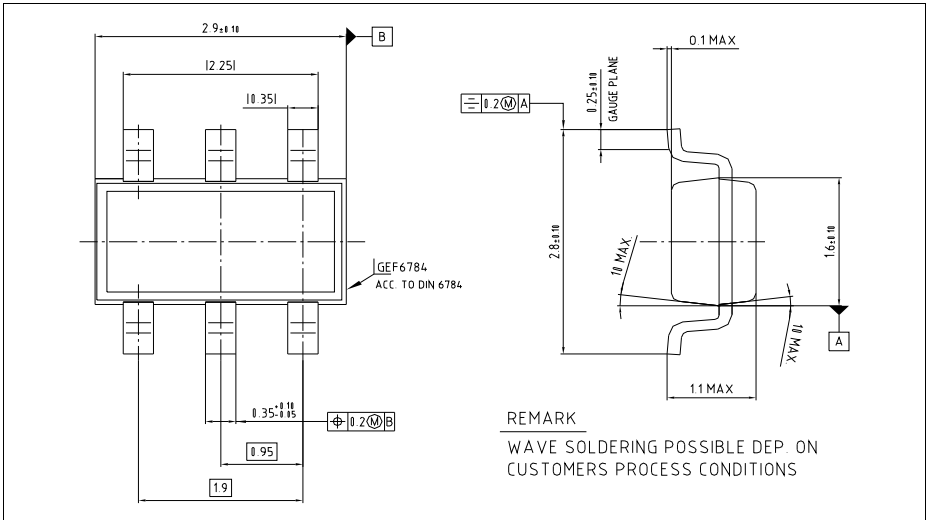


Figure 8 PG-TSOP6-6-9 (Plastic Thin Small Outline Package)

### PCB Footprint for PG-TSOP6-6-9

The following picture shows a recommendation for the PCB layout.

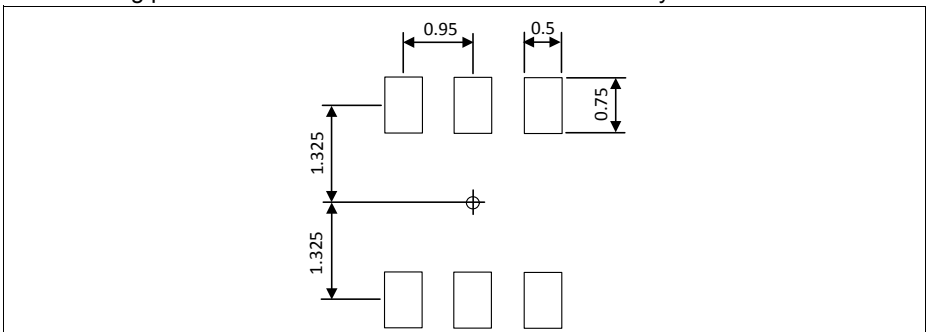


Figure 9 Footprint PG-TSOP6-6-9

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Dimensions in mm



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